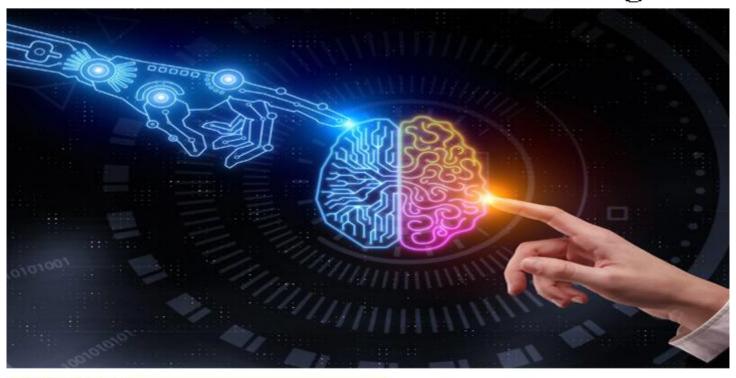
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Futuristic Trends in Artificial Intelligence



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Last date for resubmission/extended submission: 28^a August 2023

Final Acceptance Notification: within 2rd September 2023 Last date for registration: within 14ⁿ October 2023

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Last date for chapter submission:28th August 2023

Publication month: December 2023

AIM & SCOPE

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- 9. Natural Language Processing
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